

MONOLITHIC COMMON CARRIER

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ABSTRACT

A common carrier for forming multiple printheads thereon and method of forming thereof is described. The common carrier includes a carrier substrate for adhering a plurality of unprocessed, integrateable semiconductor chips. Once
10 adhered, the carrier substrate is lithographically processed to form a plurality of integrated circuit (IC) printhead chips such that alignment of the IC chips on the carrier substrate has the precision of lithographic alignment tolerances which is well within printhead alignment requirements.

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